

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	:	Basol et al.
Appl. No.	:	10/782,697
Filed	:	February 18, 2004
For	:	METHOD OF WAFER PROCESSING WITH EDGE SEED LAYER REMOVAL
Examiner	:	Michael Manh Trinh
Group Art Unit	:	2822

**RESPONSE TO OFFICE ACTION****Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed on January 26, 2007, please amend the above-captioned application as set forth herein.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.